CY7C1041BNV33

256 K × 16 Static RAM

Features

- High speed
  - t_{AA} = 12 ns
- Low active power
  - 612 mW (max.)
- Low CMOS standby power
  - 1.8 mW (max.)
- 2.0 V Data Retention (660 µW at 2.0 V retention)
- Automatic power-down when deselected
- TTL-compatible inputs and outputs
- Easy memory expansion with $\overline{CE}$ and $\overline{OE}$ features

Functional Description

The CY7C1041BNV33 is a high-performance CMOS Static RAM organized as 262,144 words by 16 bits.

Writing to the device is accomplished by taking Chip Enable ($\overline{CE}$) and Write Enable ($\overline{WE}$) inputs LOW. If Byte Low Enable ($\overline{BLE}$) is LOW, then data from I/O pins (I/O_0 through I/O_7), is written into the location specified on the address pins (A_0 through A_{17}). If Byte High Enable ($\overline{BHE}$) is LOW, then data from I/O pins (I/O_8 through I/O_{15}) is written into the location specified on the address pins (A_0 through A_{17}).

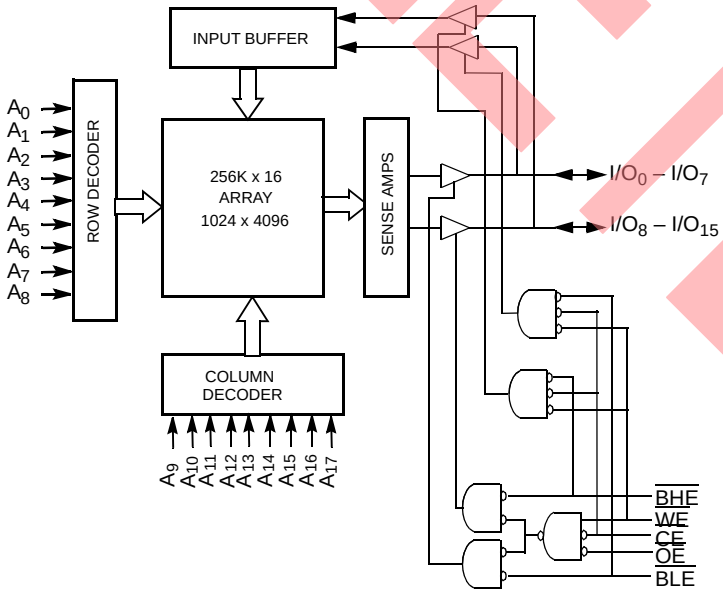
Reading from the device is accomplished by taking Chip Enable ($\overline{CE}$) and Output Enable ($\overline{OE}$) LOW while forcing the Write Enable ($\overline{WE}$) HIGH. If Byte Low Enable ($\overline{BLE}$) is LOW, then data from the memory location specified by the address pins will appear on I/O_0 to I/O_7. If Byte High Enable ($\overline{BHE}$) is LOW, then data from memory will appear on I/O_8 to I/O_{15}. See the truth table at the back of this data sheet for a complete description of read and write modes.

The input/output pins (I/O_0 through I/O_{15}) are placed in a high-impedance state when the device is deselected ($\overline{CE}$ HIGH), the outputs are disabled ($\overline{OE}$ HIGH), the $\overline{BHE}$ and $\overline{BLE}$ are disabled ($\overline{BHE}$, $\overline{BLE}$ HIGH), or during a write operation ($\overline{CE}$ LOW, and $\overline{WE}$ LOW).

The CY7C1041BNV33 is available in a standard 44-pin TSOP II package with center power and ground (revolutionary) pinout.

For a complete list of related documentation, click here.

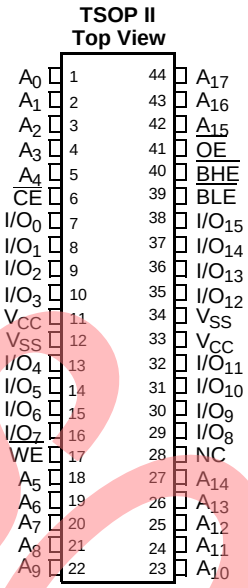
Logic Block Diagram



Contents

Pin Configuration

Figure 1. 44-pin TSOP II pinout (Top View)



Selection Guide

Description		-12
Maximum Access Time (ns)		12
Maximum Operating Current (mA)	Commercial	190
Maximum CMOS Standby Current (mA)	Commercial	0.5

Maximum Ratings

Exceeding the maximum ratings may impair the useful life of the device. These user guidelines are not tested.

Storage Temperature ..... –65 °C to +150 °C

Ambient Temperature with Power Applied ..... –55 °C to +125 °C

Supply Voltage on V_{CC} to Relative GND [1] .....–0.5 V to +4.6 V

DC Voltage Applied to Outputs in High Z State [1] .....–0.5 V to V_{CC} + 0.5 V

DC Input Voltage [1] .....–0.5 V to V_{CC} + 0.5 V

Current into Outputs (LOW) ..... 20 mA

Static discharge voltage (MIL-STD-883, method 3015) ..... > 2001 V

Latch up current ..... > 200 mA

Operating Range

Range	Ambient Temperature [2]	V_{CC}
Commercial	0 °C to +70 °C	3.3 V ± 0.3 V

Electrical Characteristics

Over the Operating Range

Parameter	Description	Test Conditions		-12		Unit
				Min	Max	
V_{OH}	Output HIGH Voltage	V_{CC} = Min, I_{OH} = –4.0 mA		2.4	–	V
V_{OL}	Output LOW Voltage	V_{CC} = Min, I_{OL} = 8.0 mA		–	0.4	V
V_{IH}	Input HIGH Voltage			2.2	V_{CC} + 0.5	V
V_{IL}	Input LOW Voltage [1]			–0.5	0.8	V
I_{IX}	Input Leakage Current	GND ≤ V_I ≤ V_{CC}		–1	+1	µA
I_{OZ}	Output Leakage Current	GND ≤ V_{OUT} ≤ V_{CC}, Output Disabled		–1	+1	µA
I_{CC}	V_{CC} Operating Supply Current	V_{CC} = Max., f = f_{MAX} = $1/t_{RC}$	Commercial	–	190	mA
I_{SB1}	Automatic CE Power-Down Current – TTL Inputs	Max. V_{CC}, $\overline{CE}$ ≥ V_{IH}, V_{IN} ≥ V_{IH} or V_{IN} ≤ V_{IL}, f = f_{MAX}		–	40	mA
I_{SB2}	Automatic CE Power-Down Current – CMOS Inputs	Max. V_{CC}, $\overline{CE}$ ≥ V_{CC} – 0.3V, V_{IN} ≥ V_{CC} – 0.3 V or V_{IN} ≤ 0.3V, f = 0	Commercial	–	0.5	mA

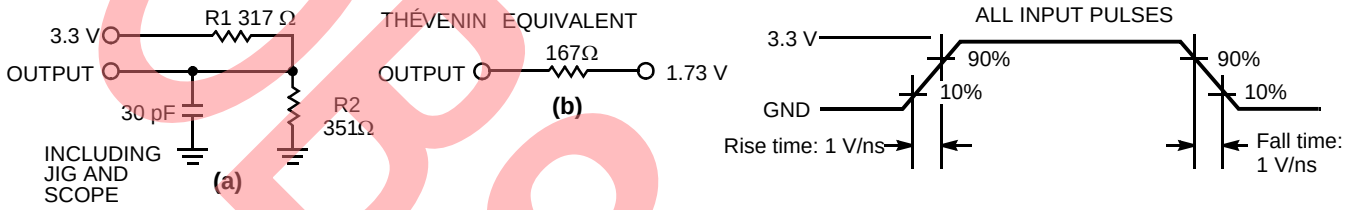
Notes
1. V_{IL} (min.) = –2.0 V for pulse durations of less than 20 ns.
2. T_A is the “Instant On” case temperature.

Capacitance

Parameter [3]	Description	Test Conditions	Max	Unit
C_{IN}	Input capacitance	T_A = 25 °C, f = 1 MHz, V_{CC} = 3.3 V	8	pF
C_{OUT}	I/O capacitance		8	pF

AC Test Loads and Waveforms

Figure 2. AC Test Loads and Waveforms



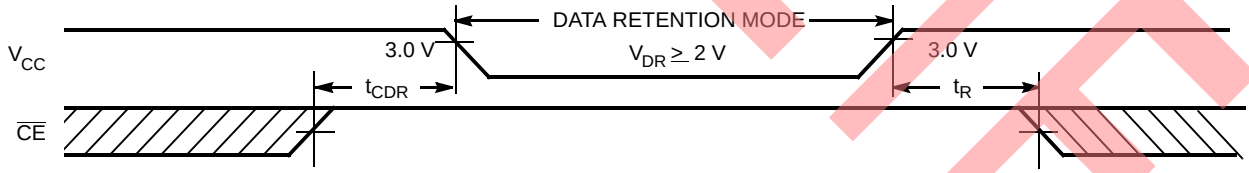
Data Retention Characteristics

Over the Operating Range

Parameter	Description	Conditions [4]	Min	Max	Unit
V_{DR}	V_{CC} for Data Retention		2.0	–	V
I_{CCDR}	Data Retention Current	V_{CC} = V_{DR} = 2.0 V, $\overline{CE} \geq V_{CC} - 0.3$ V, $V_{IN} \geq V_{CC} - 0.3$ V or $V_{IN} \leq 0.3$ V	–	330	µA
t_{CDR} [3]	Chip Deselect to Data Retention Time		0	–	ns
t_R [5]	Operation Recovery Time		t_{RC}	–	ns

Data Retention Waveform

Figure 3. Data Retention Waveform



Notes
3. Tested initially and after any design or process changes that may affect these parameters.
4. No input may exceed V_{CC} + 0.5 V.
5. $t_r \leq 3$ ns for the -12 and -15 speeds.

Switching Characteristics

Over the Operating Range

Parameter [6]	Description	-12		Unit
		Min	Max	
READ CYCLE				
t_{RC}	Read Cycle Time	12	–	ns
t_{AA}	Address to Data Valid	–	12	ns
t_{OHA}	Data Hold from Address Change	3	–	ns
t_{ACE}	$\overline{CE}$ LOW to Data Valid	–	12	ns
t_{DOE}	$\overline{OE}$ LOW to Data Valid	–	6	ns
t_{LZOE}	$\overline{OE}$ LOW to Low Z	0	–	ns
t_{HZOE}	$\overline{OE}$ HIGH to High Z [7, 8]	–	6	ns
t_{LZCE}	$\overline{CE}$ LOW to Low Z [8]	3	–	ns
t_{HZCE}	$\overline{CE}$ HIGH to High Z [7, 8]	–	6	ns
t_{PU}	$\overline{CE}$ LOW to Power-Up	0	–	ns
t_{PD}	$\overline{CE}$ HIGH to Power-Down	–	12	ns
t_{DBE}	Byte Enable to Data Valid	–	6	ns
t_{LZBE}	Byte Enable to Low Z	0	–	ns
t_{HZBE}	Byte Disable to High Z	–	6	ns
WRITE CYCLE [9, 10]				
t_{WC}	Write Cycle Time	12	–	ns
t_{SCE}	$\overline{CE}$ LOW to Write End	10	–	ns
t_{AW}	Address Set-Up to Write End	10	–	ns
t_{HA}	Address Hold from Write End	0	–	ns
t_{SA}	Address Set-Up to Write Start	0	–	ns
t_{PWE}	$\overline{WE}$ Pulse Width	10	–	ns
t_{SD}	Data Set-Up to Write End	7	–	ns
t_{HD}	Data Hold from Write End	0	–	ns
t_{LZWE}	$\overline{WE}$ HIGH to Low Z [8]	3	–	ns
t_{HZWE}	$\overline{WE}$ LOW to High Z [7, 8]	–	6	ns
t_{BW}	Byte Enable to End of Write	10	–	ns

Notes

6. Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5 V, input pulse levels of 0 to 3.0 V, and output loading of the specified I_{OL}/I_{OH} and 30-pF load capacitance.
7. t_{HZOE}, t_{HZCE}, and t_{HZWE} are specified with a load capacitance of 5 pF as in part (b) of Figure 2 on page 5. Transition is measured ±500 mV from steady-state voltage.
8. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE}, t_{HZOE} is less than t_{LZOE}, and t_{HZWE} is less than t_{LZWE} for any given device.
9. The internal write time of the memory is defined by the overlap of $\overline{CE}$ LOW, and $\overline{WE}$ LOW. $\overline{CE}$ and $\overline{WE}$ must be LOW to initiate a write, and the transition of either of these signals can terminate the write. The input data set-up and hold timing should be referenced to the leading edge of the signal that terminates the write.
10. The minimum write cycle time for Write Cycle No. 3 ($\overline{WE}$ controlled, $\overline{OE}$ LOW) is the sum of t_{HZWE} and t_{SD}.

Switching Waveforms

Figure 4. Read Cycle No. 1 [11, 12]

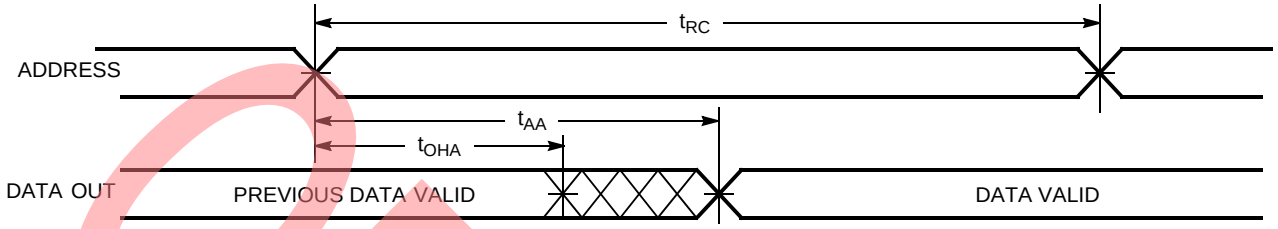
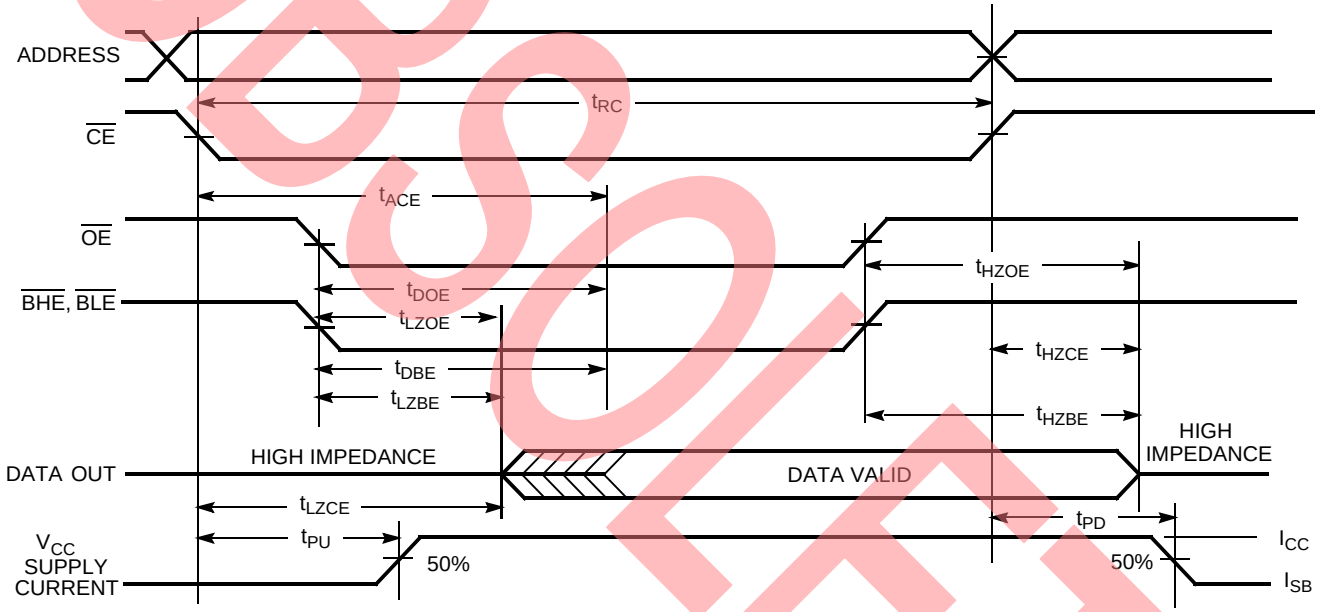


Figure 5. Read Cycle No. 2 ($\overline{OE}$ Controlled) [12, 13]



Notes
11. Device is continuously selected. $\overline{OE}$, $\overline{CE}$, $\overline{BHE}$ and/or $\overline{BHE}$ = V_{IL}.
12. $\overline{WE}$ is HIGH for read cycle.
13. Address valid prior to or coincident with $\overline{CE}$ transition LOW.

Switching Waveforms (continued)

Figure 6. Write Cycle No. 1 ($\overline{CE}$ Controlled) [14, 15]

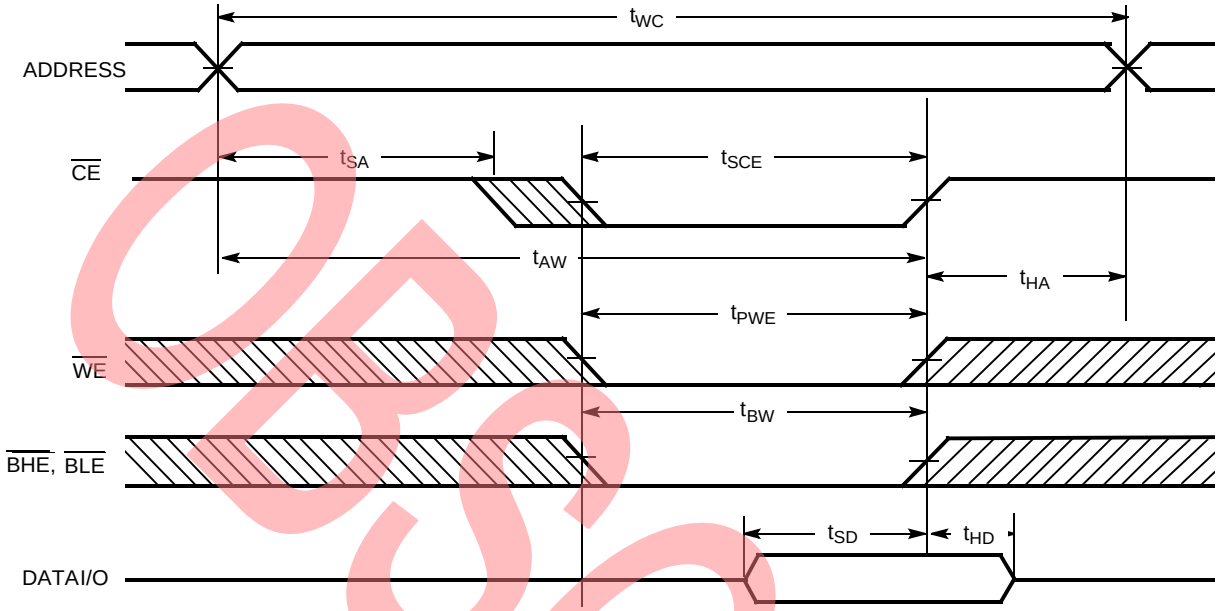
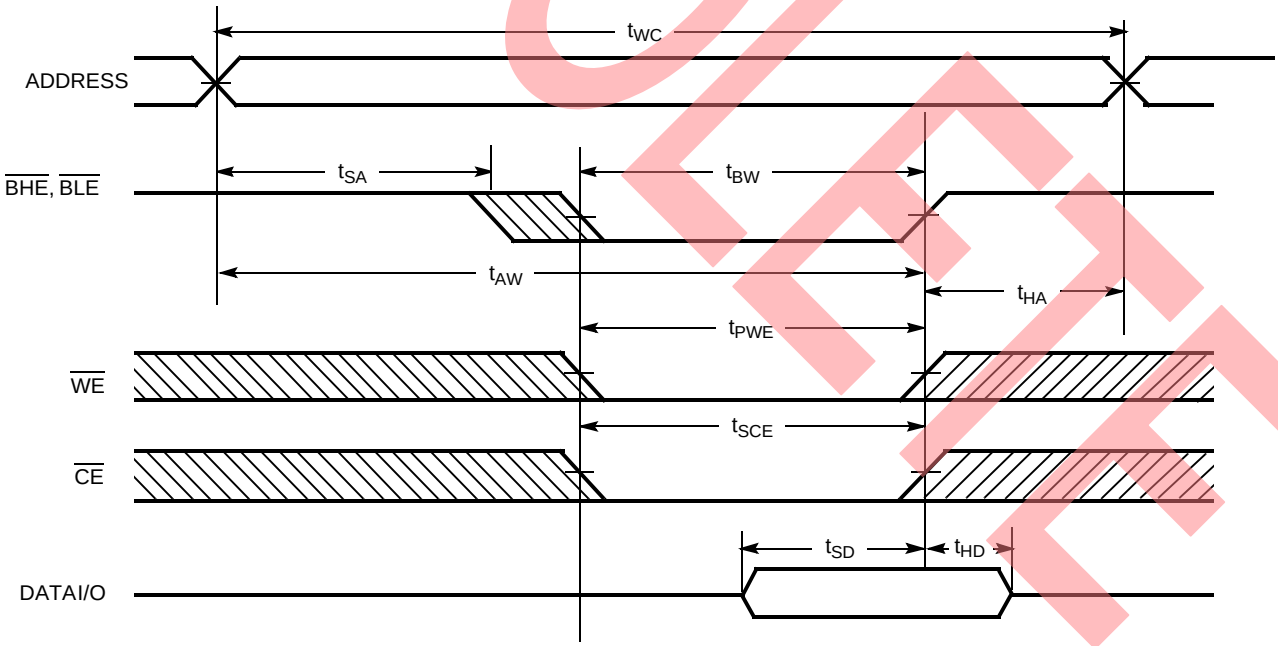


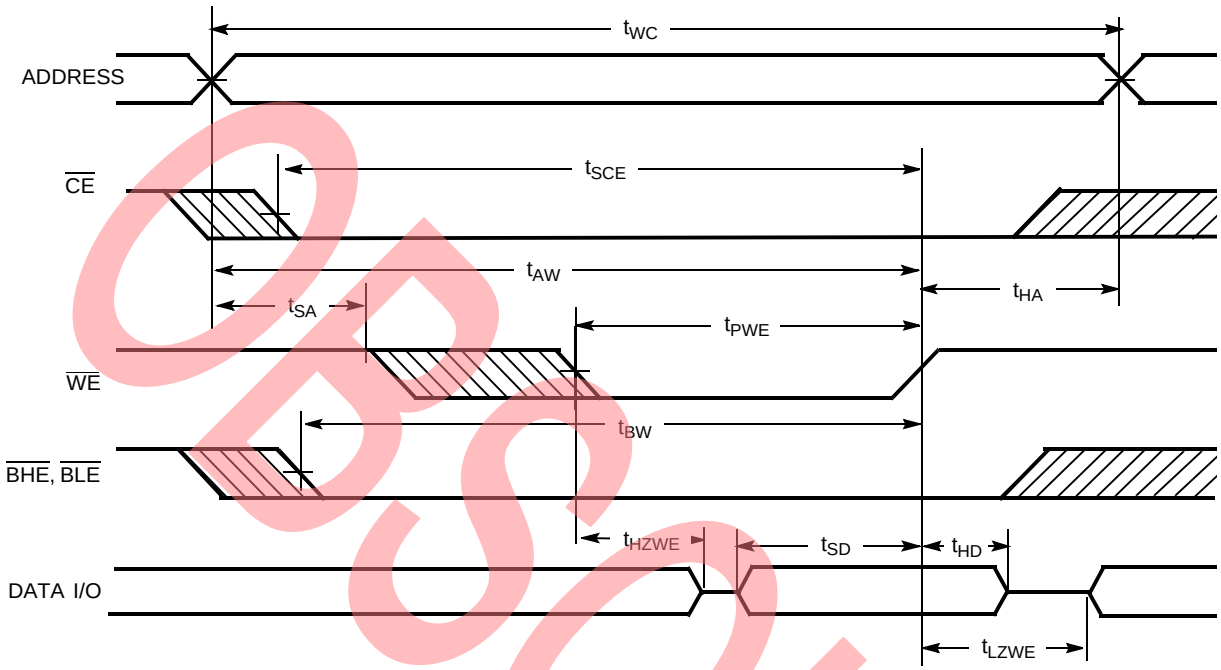
Figure 7. Write Cycle No. 2 ($\overline{BLE}$ or $\overline{BHE}$ Controlled)



Notes
14. Data I/O is high-impedance if $\overline{OE}$ or $\overline{BHE}$ and/or $\overline{BLE}$= V_{IH}.
15. If $\overline{CE}$ goes HIGH simultaneously with $\overline{WE}$ going HIGH, the output remains in a high–impedance state.

Switching Waveforms (continued)

Figure 8. Write Cycle No. 3 ($\overline{WE}$ Controlled, $\overline{OE}$ LOW)



Truth Table

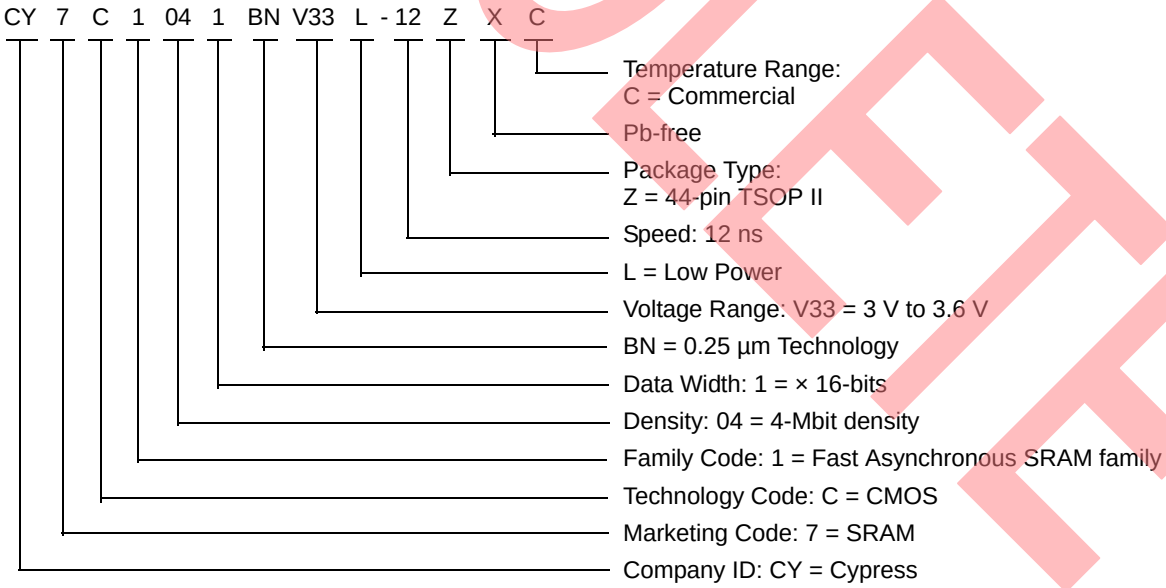
$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	$\overline{BLE}$	$\overline{BHE}$	I/O_0–I/O_7	I/O_8–I/O_{15}	Mode	Power
H	X	X	X	X	High Z	High Z	Power Down	Standby (I_{SB})
L	L	H	L	L	Data Out	Data Out	Read All Bits	Active (I_{CC})
L	L	H	L	H	Data Out	High Z	Read Lower Bits Only	Active (I_{CC})
L	L	H	H	L	High Z	Data Out	Read Upper Bits Only	Active (I_{CC})
L	X	L	L	L	Data In	Data In	Write All Bits	Active (I_{CC})
L	X	L	L	H	Data In	High Z	Write Lower Bits Only	Active (I_{CC})
L	X	L	H	L	High Z	Data In	Write Upper Bits Only	Active (I_{CC})
L	H	H	X	X	High Z	High Z	Selected, Outputs Disabled	Active (I_{CC})

Ordering Information

Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
12	CY7C1041BNV33L-12ZXC	51-85087	44-pin TSOP II (Pb-free)	Commercial

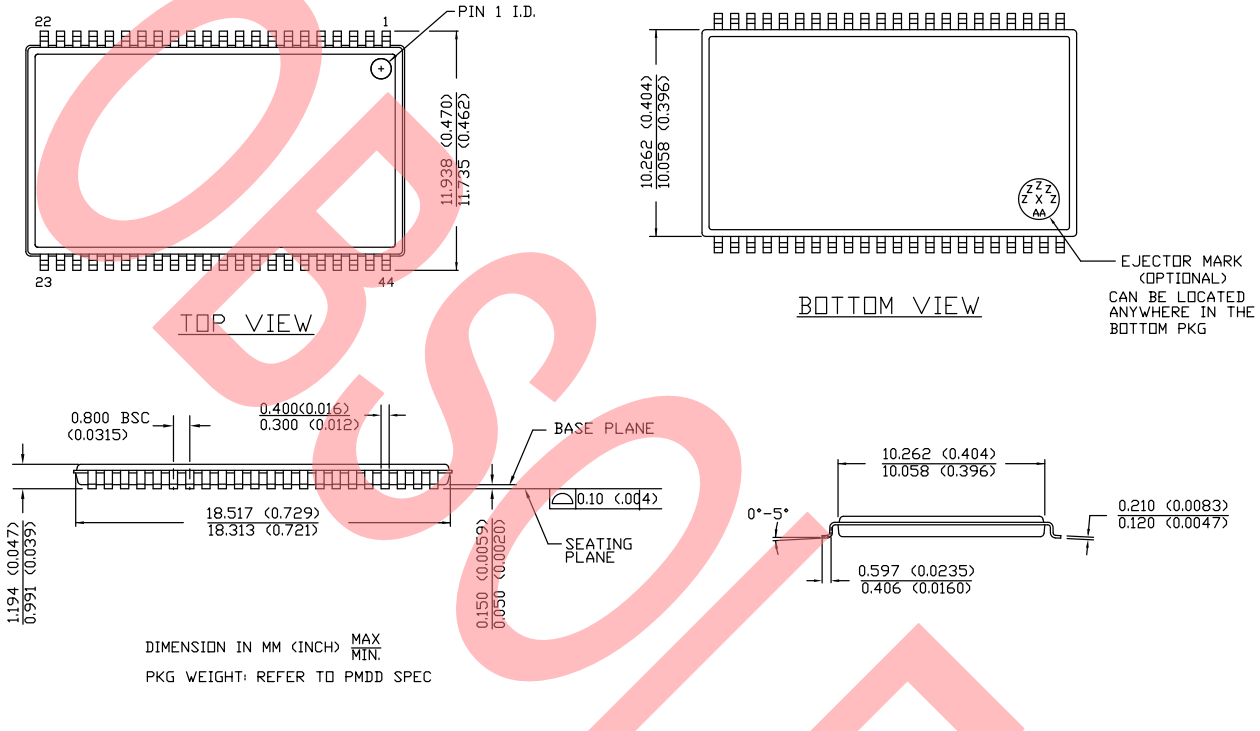
Please contact local sales representative regarding availability of these parts.

Ordering Code Definitions



Package Diagrams

Figure 9. 44-pin TSOP II Package Outline, 51-85087



Acronyms

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
$\overline{CE}$	Chip Enable
I/O	Input/Output
$\overline{OE}$	Output Enable
SRAM	Static Random Access Memory
TTL	Transistor-Transistor Logic
TSOP	Thin Small-Outline Package
$\overline{WE}$	Write Enable

Document Conventions

Units of Measure

Symbol	Unit of Measure
°C	degree Celsius
MHz	megahertz
µA	microampere
µF	microfarad
µs	microsecond
µW	microwatt
mA	milliampere
ms	millisecond
mW	milliwatt
ns	nanosecond
Ω	ohm
%	percent
pF	picofarad
V	volt
W	watt

Document History Page

Document Title: CY7C1041BNV33, 256 K × 16 Static RAM Document Number: 001-06434				
Revision	**ECN**	**Orig. of Change**	**Submission Date**	**Description of Change**
**	423877	NXR	See ECN	New data sheet.
*A	2899016	VKN	See ECN	Removed Industrial grade temperature related information. Removed 15 ns speed bin related information. Updated Ordering Information. Updated Package Diagrams.
*B	3109184	AJU	12/13/2010	Added Ordering Code Definitions.
*C	3210222	PRAS	03/30/2011	Updated Selection Guide. Added Acronyms and Units of Measure. Updated in new template.
*D	3232637	PRAS	05/04/2011	Updated Electrical Characteristics: Fixed unit for Input Leakage current and Output Leakage current from mA to µA.
*E	3403051	AJU	10/12/2011	Updated Ordering Information (Removed prune part number CY7C1041BNV33L-12VXC). Updated Package Diagrams.
*F	4337921	VINI	04/09/2014	Updated Maximum Ratings: Added “Static discharge voltage” and “Latch up current” details. Updated Package Diagrams: spec 51-85082 – Changed revision from *D to *E. spec 51-85087 – Changed revision from *D to *E. Updated to new template. Completing Sunset Review.
*G	4578500	VINI	11/25/2014	Updated Functional Description: Added “For a complete list of related documentation, click here.” at the end.
*H	4736197	VINI	04/23/2015	Removed “44-pin SOJ package” details in all instances across the document. Updated Package Diagrams: Removed spec 51-85082 *E. Updated to new template. Completing Sunset Review.
*I	6171990	VINI	05/11/2018	Obsolete datasheet

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